KOREAN INTERNATIONAL SEMICONDUCTOR CONFERENCE & EXHIBITION ON MANUFACTURING TECHNOLOGY 2024

KISM 2024 BUSAN

November 11 (Mon.) - 15 (Fri.), 2024
Paradise Hotel Busan & Grand Josun Busan
(Haeundae Beach) | Busan, Korea

Session Title:	[WeC2] Hybrid Bonding & Evaluations
Session Date:	November 13 (Wed.), 2024
Session Time:	14:10-15:50
Session Room:	Room C (Grand Ballroom 3, 2F, Paradise Hotel Busan)
Session Chair:	Dr. Kwang-Seong Choi (ETRI, Korea)

[WeC2-1] [Invited] 14:10-14:40

3D & Heterogeneous Integration at CEA-Leti for the Co-Optimization of the System and the Technology

Jean-Charles Souriau (Univ. Grenoble Alpes, France)

[WeC2-2] [Invited] 14:40-15:10

Recent Advances in Hybrid Bonding Technologies for Advanced Packaging

Minwoo Rhee (Samsung Electronics Co., Ltd., Korea)

[WeC2-3] [Invited] 15:10-15:30

Nanoparticle-Based Thermal Interface Materials : Alignment Strategy for Improvement of Thermal Conductivity

Uijin Jung, Sangmin Kim, and Jinsub Park (Hanyang Univ., Korea)

[WeC2-4] 15:30-15:50

Electrical and Material Characterization of RDL on the PSPI Packaging Substrate

Sunbum Kim, Gyulee Kim, Dayoung Oh, Dugkyu Han, Kyoungyeon Min, and Changhwan Choi (Hanyang Univ., Korea)